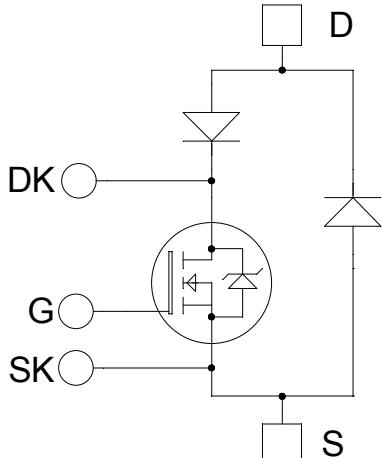
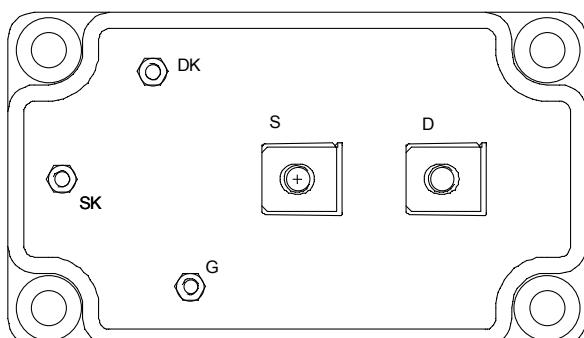


*Single switch  
Series & SiC parallel diodes  
MOSFET Power Module*

**V<sub>DSS</sub> = 1000V**  
**R<sub>DSon</sub> = 65mΩ typ @ T<sub>j</sub> = 25°C**  
**I<sub>D</sub> = 145A @ T<sub>c</sub> = 25°C**



G, SK and DK terminals are for control signals only  
(not for power)



## Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

## Features

- **Power MOS 7® MOSFETs**
  - Low R<sub>DSon</sub>
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- **SiC Parallel Schottky Diode**
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
  - Positive temperature coefficient on VF
- Kelvin source for easy drive
- Kelvin drain for voltage monitoring
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
  - M3 power connectors
- High level of integration
- AlN substrate for improved MOSFET thermal performance

## Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

All ratings @ T<sub>j</sub> = 25°C unless otherwise specified

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

**Absolute maximum ratings**

Symbol	Parameter		Max ratings	Unit
V <sub>DSS</sub>	Drain - Source Breakdown Voltage		1000	V
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> = 25°C	145	A
		T <sub>c</sub> = 80°C	110	
I <sub>DM</sub>	Pulsed Drain current		580	
V <sub>GS</sub>	Gate - Source Voltage		±30	V
R <sub>DSON</sub>	Drain - Source ON Resistance		78	mΩ
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> = 25°C	3250	W
I <sub>AR</sub>	Avalanche current (repetitive and non repetitive)		30	A
E <sub>AR</sub>	Repetitive Avalanche Energy		50	mJ
E <sub>AS</sub>	Single Pulse Avalanche Energy		3200	

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1000V	T <sub>j</sub> = 25°C		400	μA
		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 800V	T <sub>j</sub> = 125°C		2	mA
R <sub>DSON</sub>	Drain – Source on Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 72.5A		65	78	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 20mA	3		5	V
I <sub>GSS</sub>	Gate – Source Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0V			±400	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 25V f = 1MHz		28.5		nF
C <sub>oss</sub>	Output Capacitance			5.08		
C <sub>rss</sub>	Reverse Transfer Capacitance			0.9		
Q <sub>g</sub>	Total gate Charge	V <sub>GS</sub> = 10V V <sub>Bus</sub> = 500V I <sub>D</sub> = 145A		1068		nC
Q <sub>gs</sub>	Gate – Source Charge			136		
Q <sub>gd</sub>	Gate – Drain Charge			692		
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = 15V V <sub>Bus</sub> = 670V I <sub>D</sub> = 145A R <sub>G</sub> = 0.75Ω		18		ns
T <sub>r</sub>	Rise Time			14		
T <sub>d(off)</sub>	Turn-off Delay Time			140		
T <sub>f</sub>	Fall Time			55		
E <sub>on</sub>	Turn-on Switching Energy	Inductive switching @ 25°C V <sub>GS</sub> = 15V, V <sub>Bus</sub> = 670V I <sub>D</sub> = 145A, R <sub>G</sub> = 0.75Ω		2.9		mJ
E <sub>off</sub>	Turn-off Switching Energy			2.9		
E <sub>on</sub>	Turn-on Switching Energy	Inductive switching @ 125°C V <sub>GS</sub> = 15V, V <sub>Bus</sub> = 670V I <sub>D</sub> = 145A, R <sub>G</sub> = 0.75Ω		4.8		mJ
E <sub>off</sub>	Turn-off Switching Energy			3.9		

**Series diode ratings and characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit	
V <sub>RRM</sub>	Maximum Peak Repetitive Reverse Voltage			200			V	
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> =200V	T <sub>j</sub> = 25°C			350	µA	
			T <sub>j</sub> = 125°C			600		
I <sub>F</sub>	DC Forward Current		T <sub>c</sub> = 80°C		120		A	
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 120A			1.1	1.15	V	
		I <sub>F</sub> = 240A			1.4			
		I <sub>F</sub> = 120A	T <sub>j</sub> = 125°C		0.9			
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 120A V <sub>R</sub> = 133V di/dt = 400A/µs	T <sub>j</sub> = 25°C		31		ns	
			T <sub>j</sub> = 125°C		60			
Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>j</sub> = 25°C		120		nC	
			T <sub>j</sub> = 125°C		500			

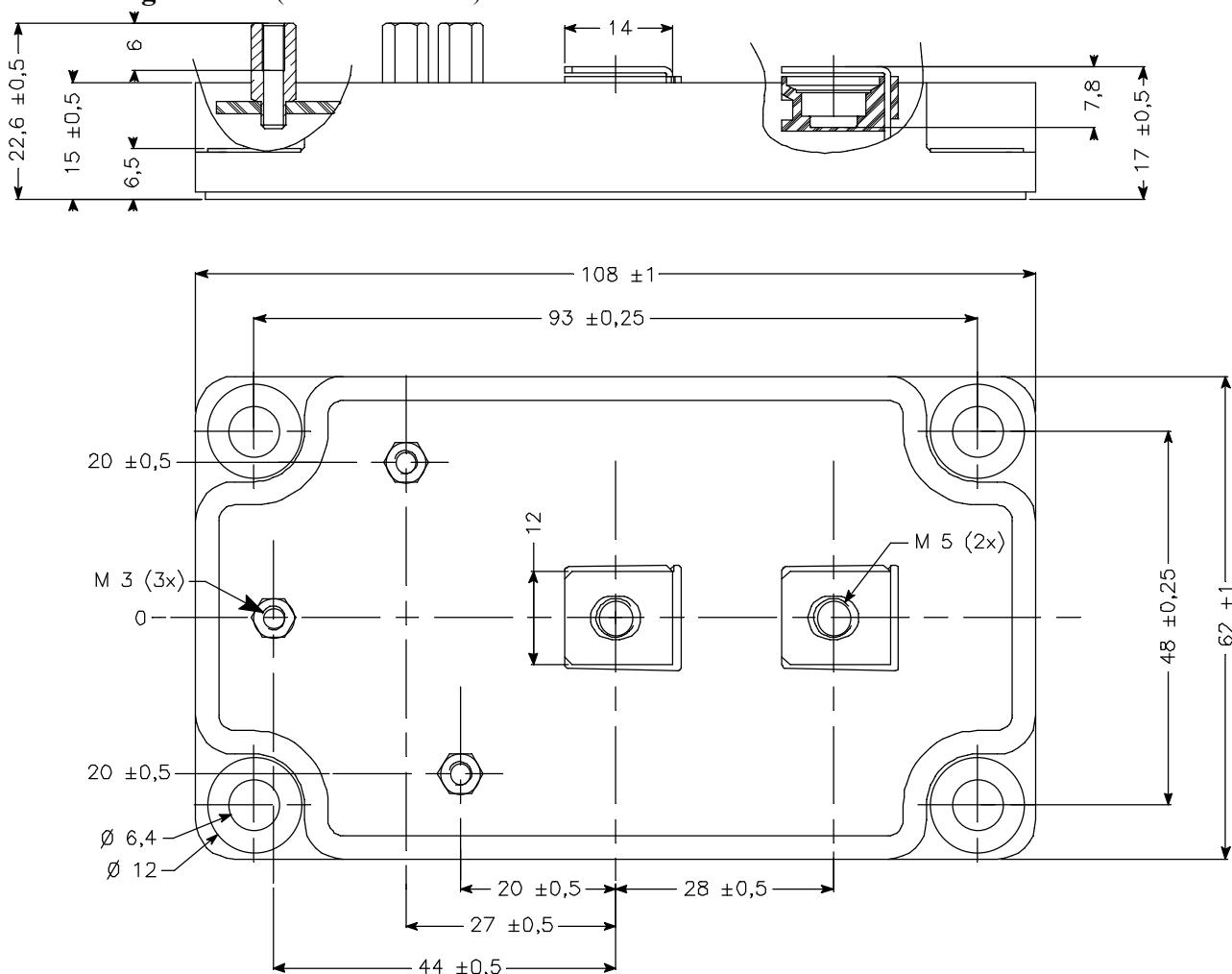
**SiC Parallel diode ratings and characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V <sub>RRM</sub>	Maximum Peak Repetitive Reverse Voltage			1200			V
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> =1200V	T <sub>j</sub> = 25°C		384	2400	µA
			T <sub>j</sub> = 125°C		672	12000	
I <sub>F</sub>	DC Forward Current		T <sub>c</sub> = 125°C		120		A
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 120A	T <sub>j</sub> = 25°C		1.6	1.8	V
			T <sub>j</sub> = 175°C		2.3	3.0	
Q <sub>C</sub>	Total Capacitive Charge	I <sub>F</sub> = 120A, V <sub>R</sub> = 600V di/dt = 5000A/µs			480		nC
C	Total Capacitance	f = 1MHz, V <sub>R</sub> = 200V			1152		pF
		f = 1MHz, V <sub>R</sub> = 400V			828		

**Thermal and package characteristics**

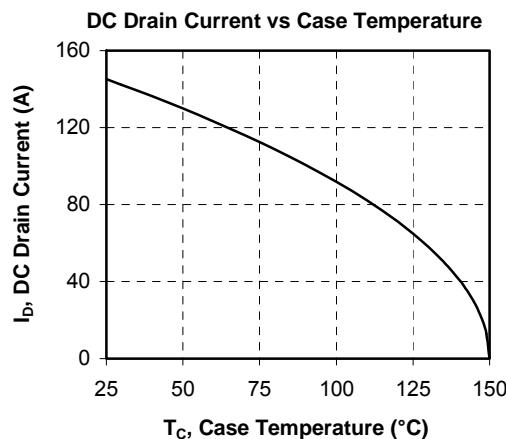
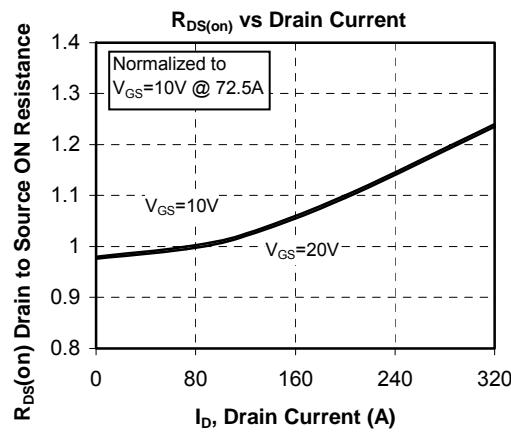
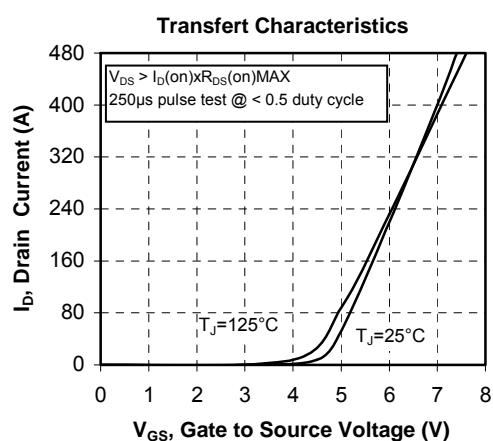
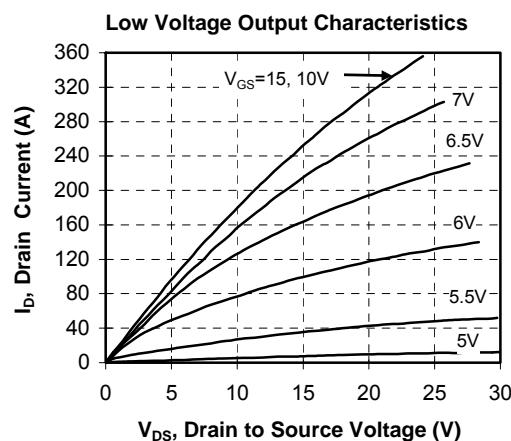
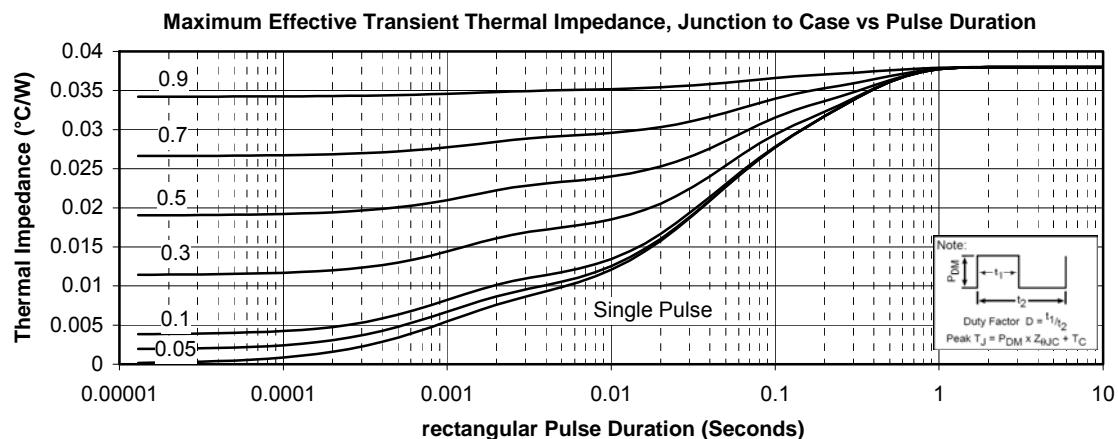
Symbol	Characteristic		Min	Typ	Max	Unit
R <sub>thJC</sub>	Junction to Case Thermal Resistance	Transistor			0.038	°C/W
		Series diode			0.46	
		SiC Parallel diode			0.18	
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t = 1 min, I <sub>isol</sub> <1mA, 50/60Hz	4000				V
T <sub>J</sub>	Operating junction temperature range	-40		150		°C
T <sub>STG</sub>	Storage Temperature Range	-40		125		
T <sub>C</sub>	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
			M3	1	1.5	
Wt	Package Weight				280	g

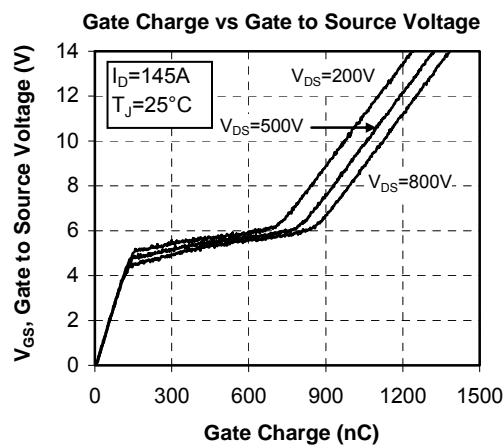
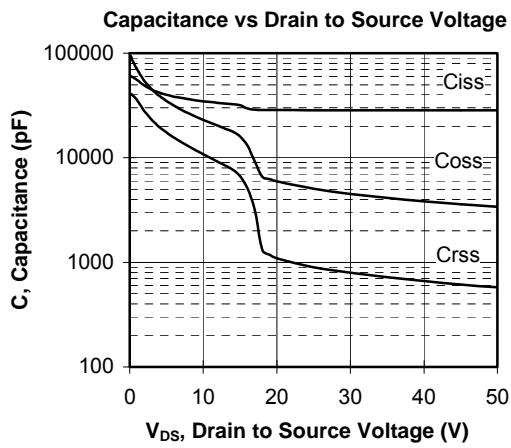
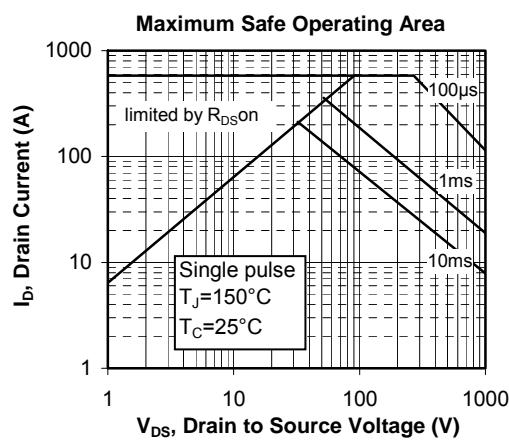
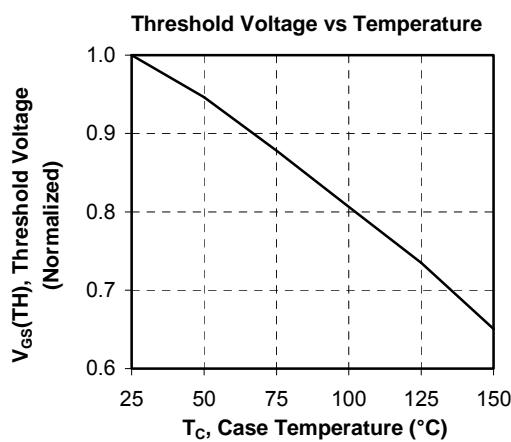
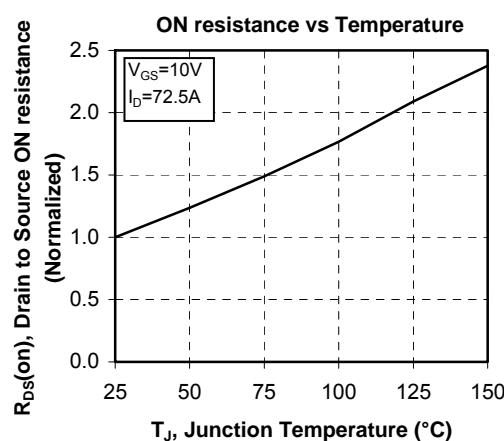
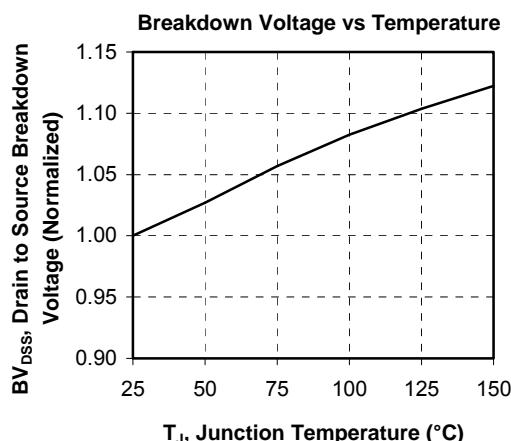
## SP6 Package outline (dimensions in mm)

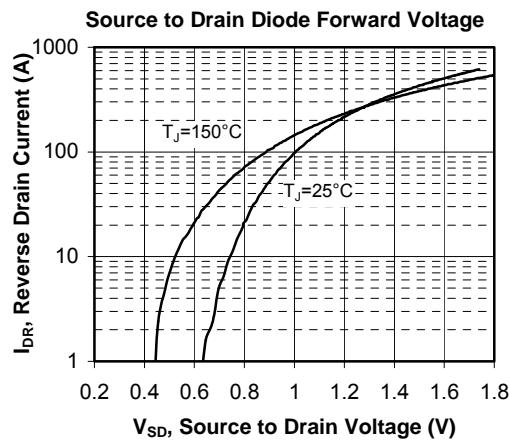
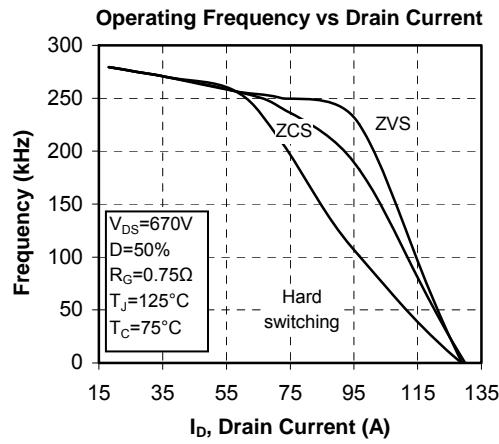
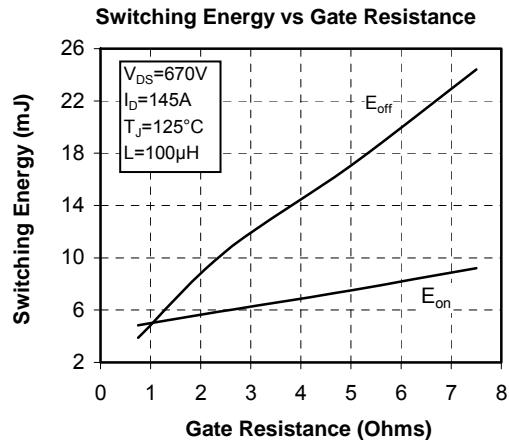
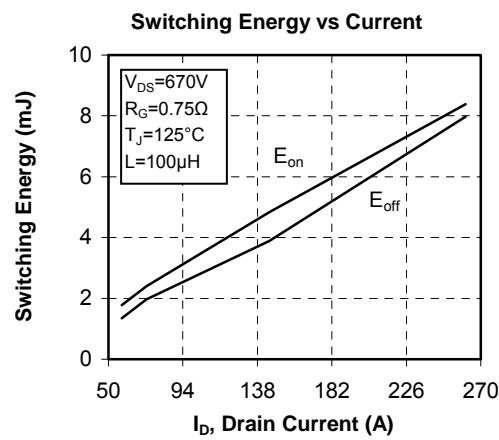
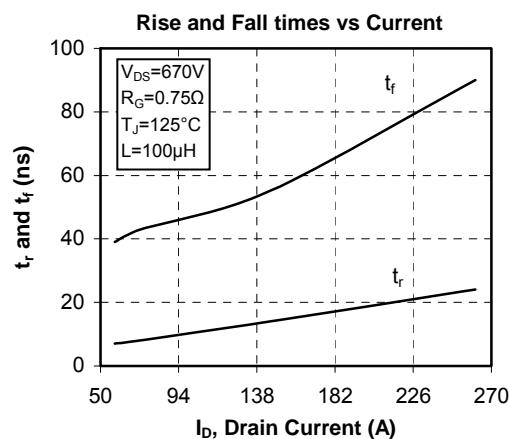
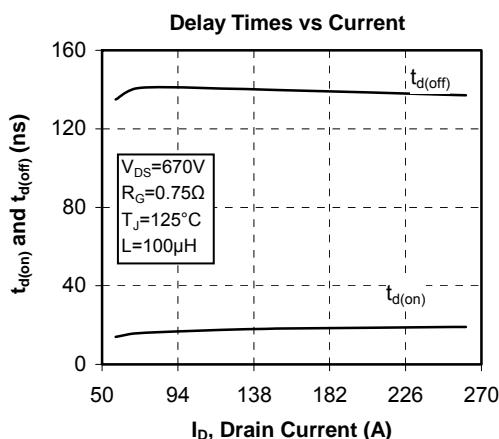


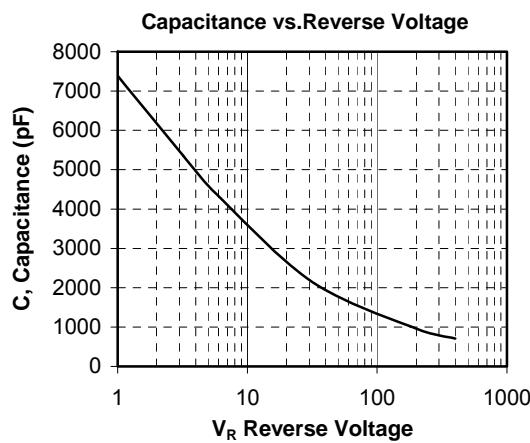
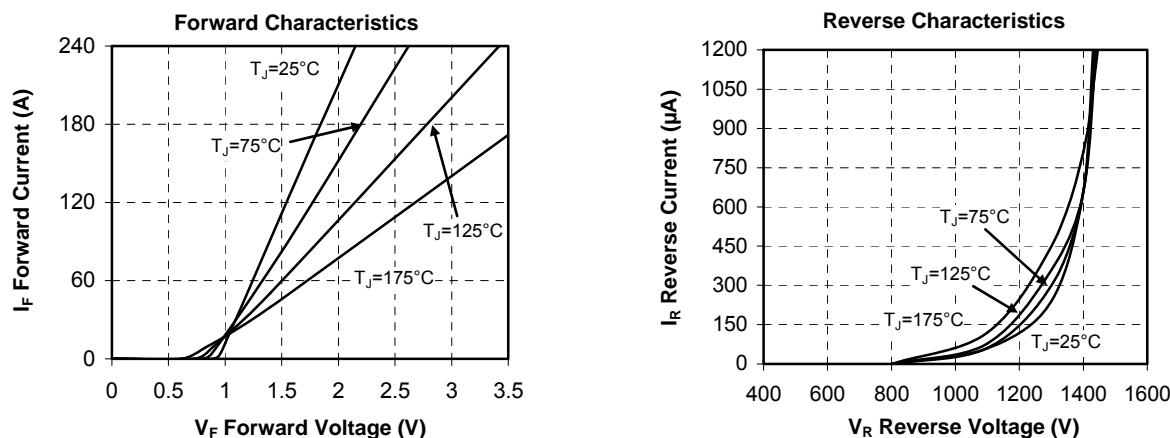
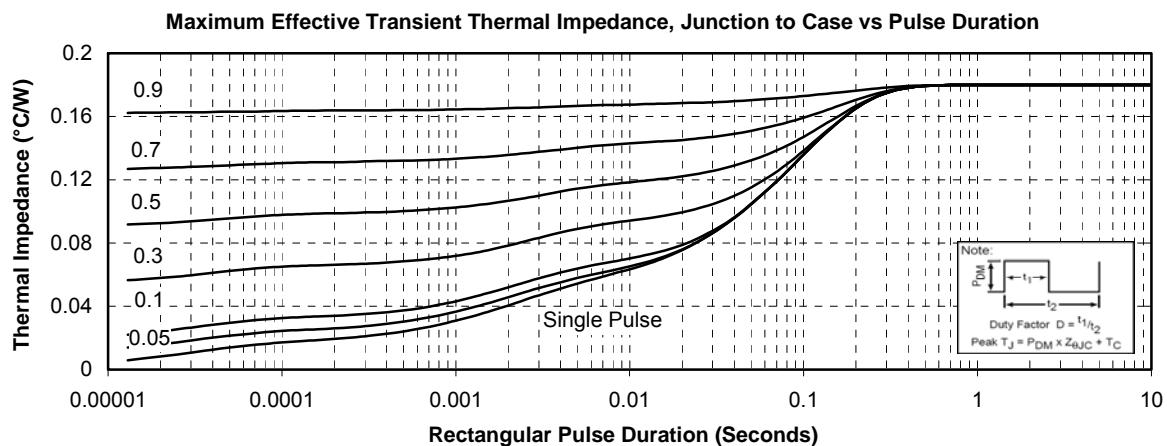
See application note APT0601 - Mounting Instructions for SP6 Power Modules on [www.microsemi.com](http://www.microsemi.com)

### Typical MOSFET Performance Curve







**Typical SiC Diode Performance Curve**


Microsemi reserves the right to change, without notice, the specifications and information contained herein

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